

Fig. 1

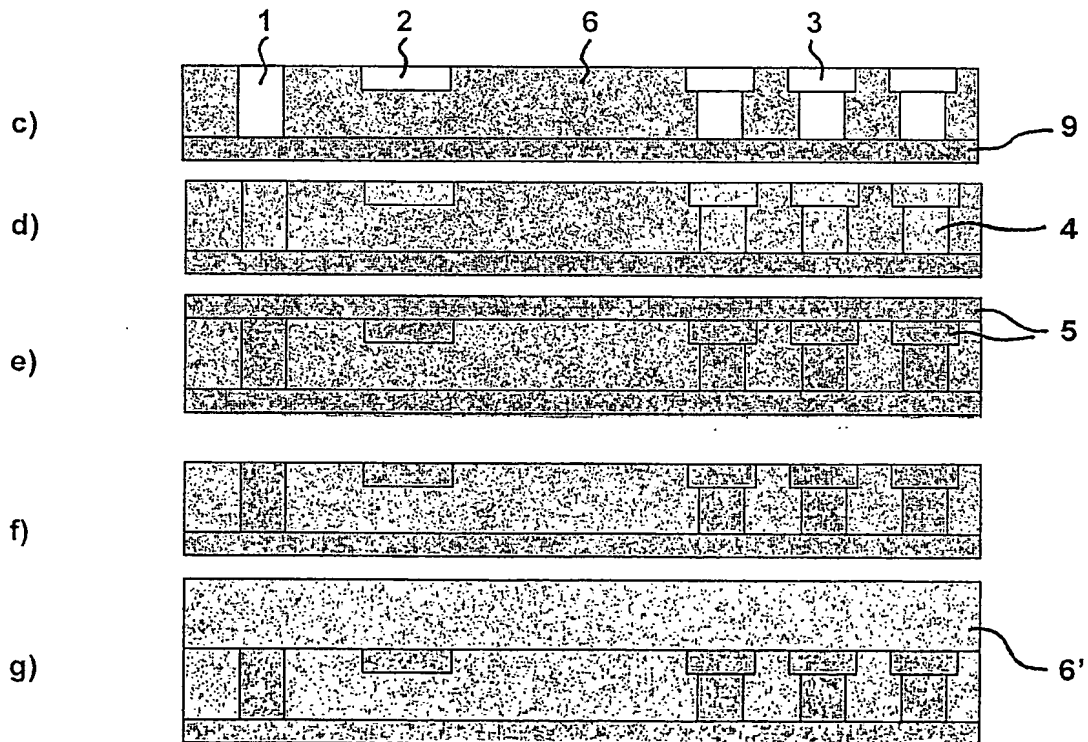


Fig. 2

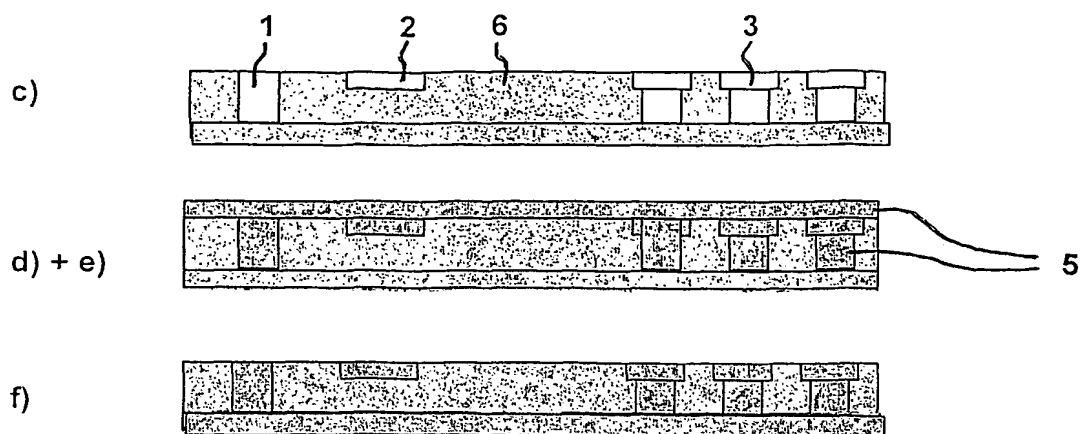


Fig. 3

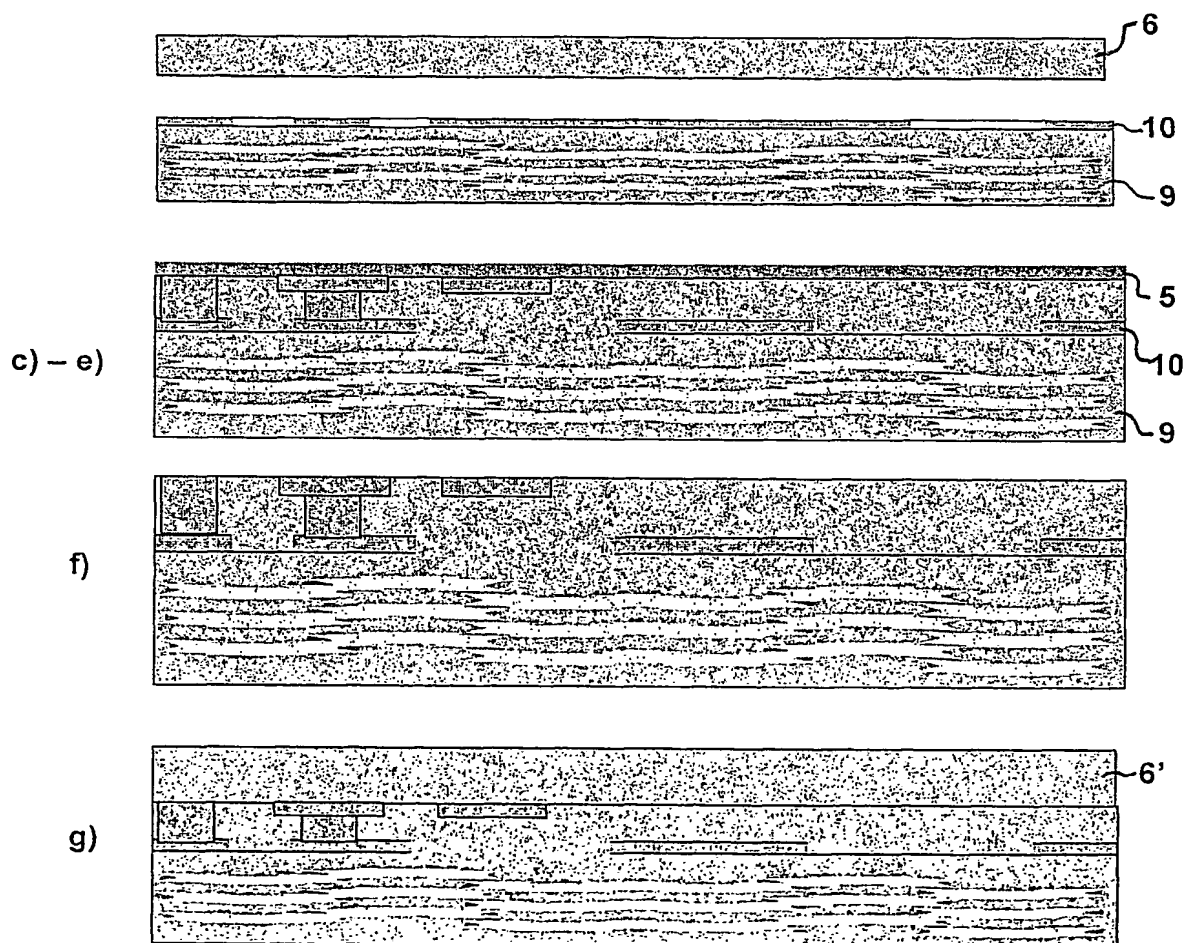


Fig. 4

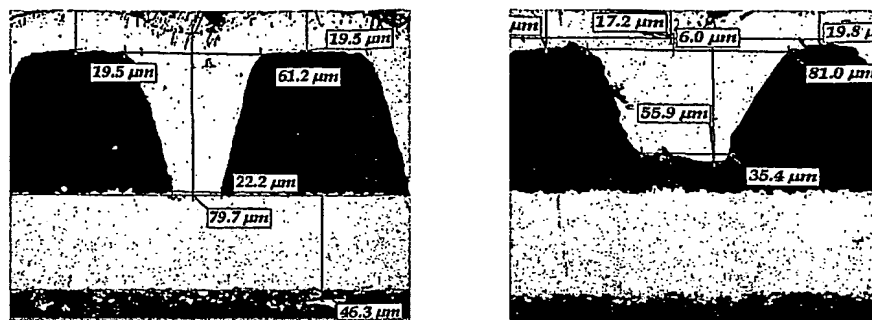


Fig. 5

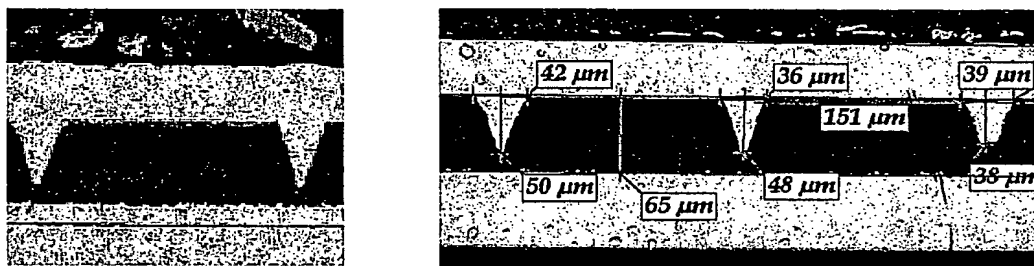


Fig. 6

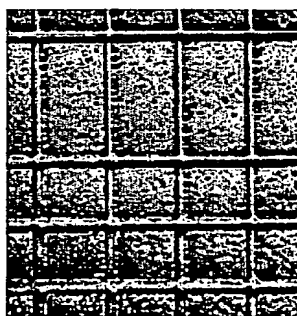


Fig. 7

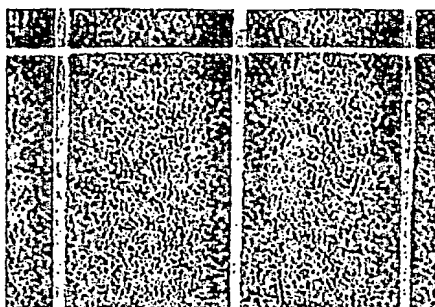


Fig. 8

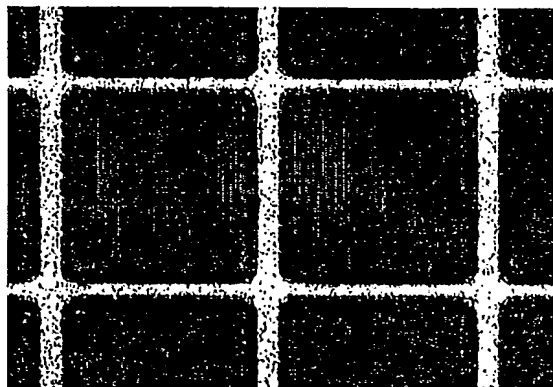
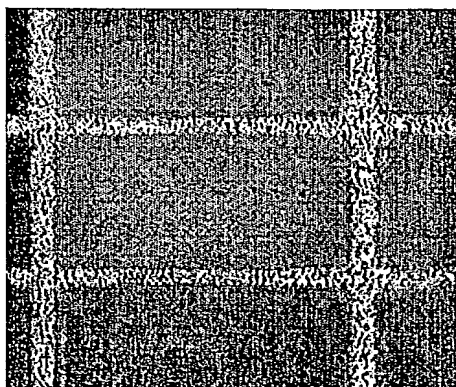


Fig. 9

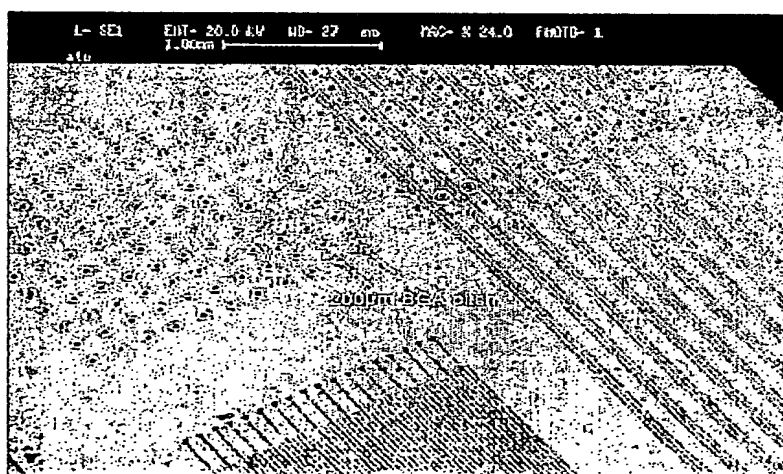


Fig. 10

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Fig. 11

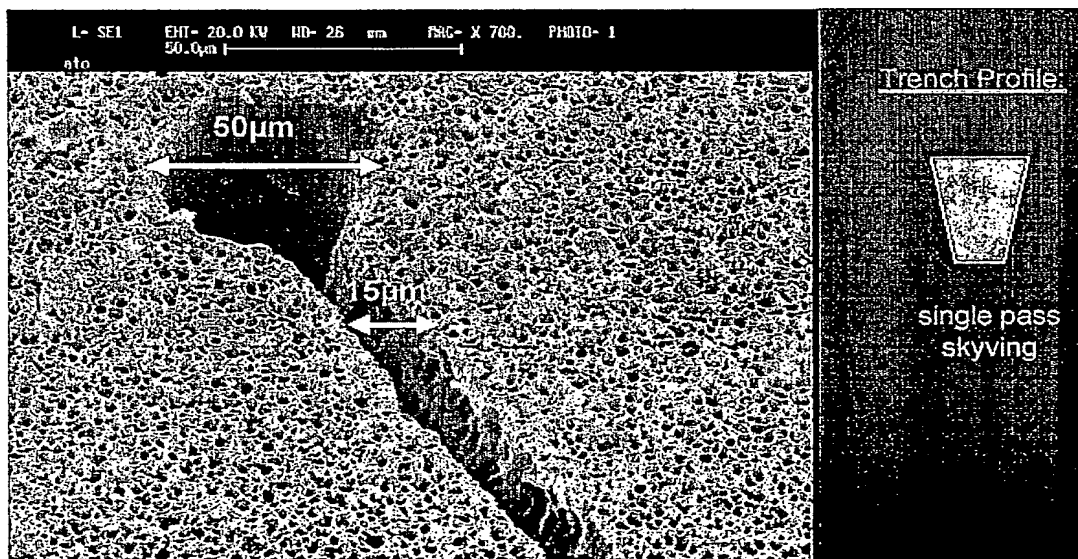
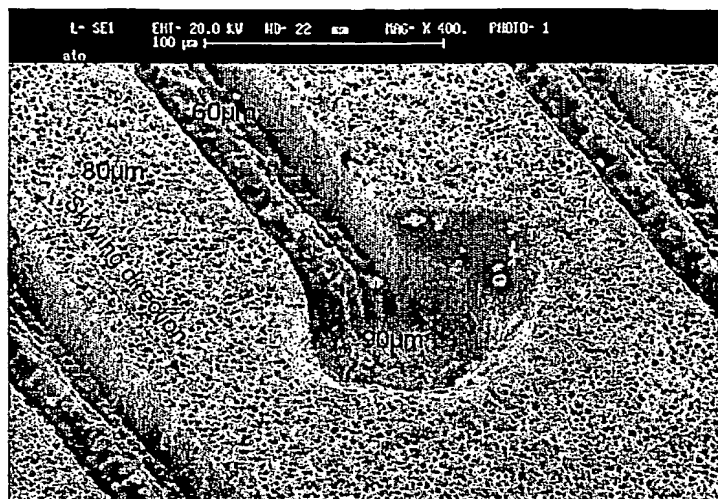
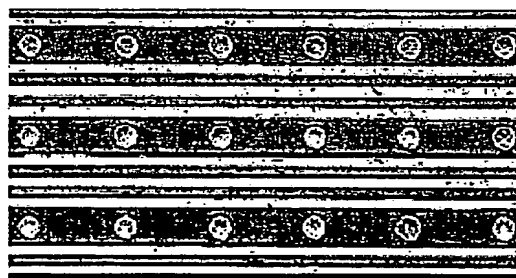


Fig. 12

Via² - Process**Multi pass skiving – before laser polish - 0.8 mm BGA****SEM – Detail of hole trench intersection****Trench Profile****Multiple pass skyving****polished****Several different
laser routines are
possible.****Fig. 13****Fig. 14****BEST AVAILABLE COPY**

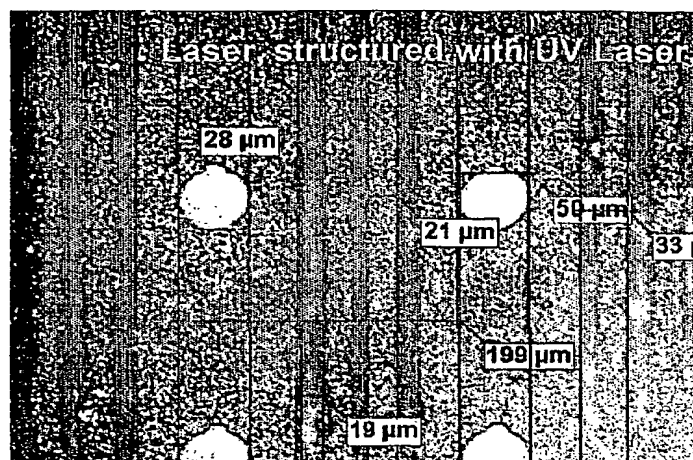


Fig. 15

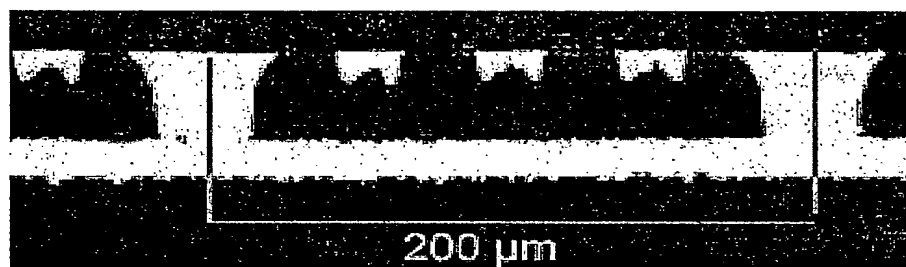


Fig. 16

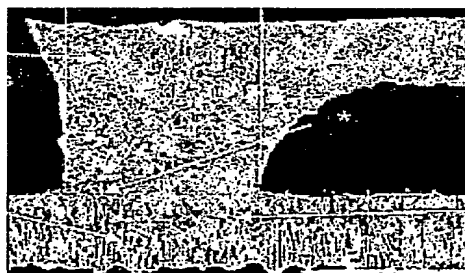


Fig. 17

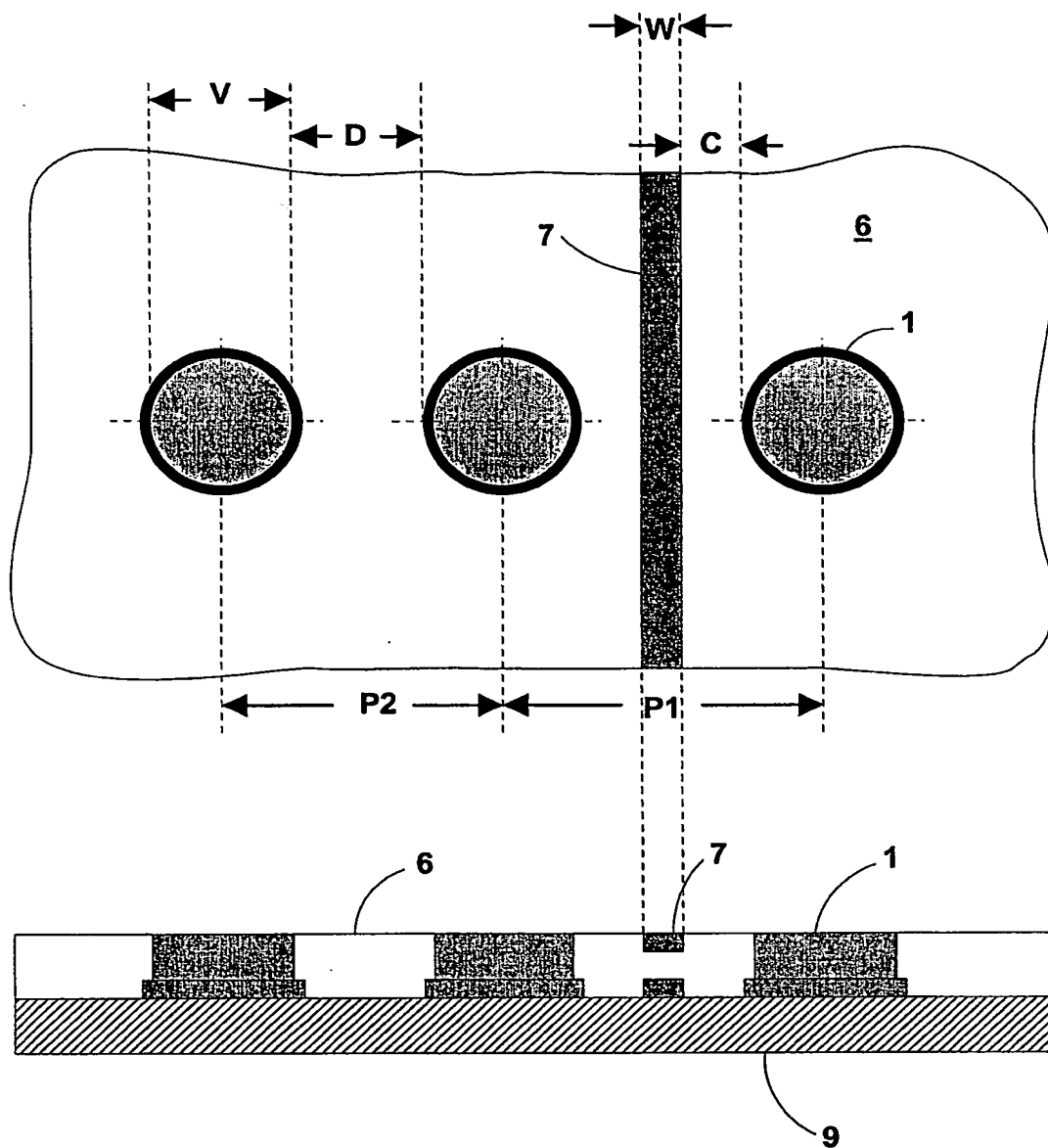


Fig. 18